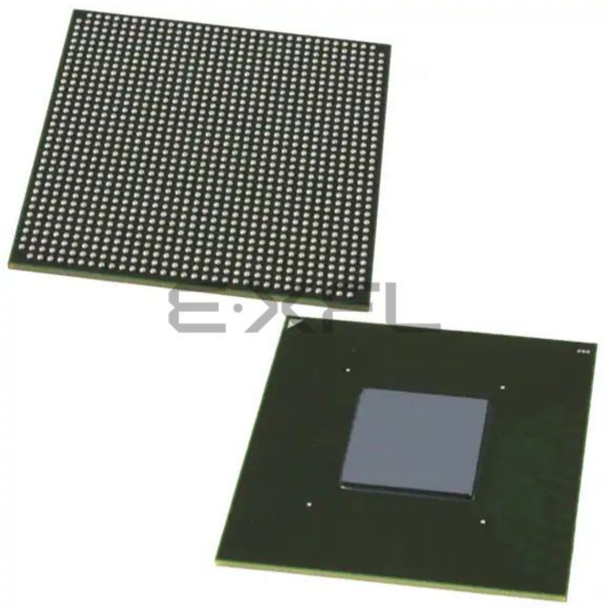


Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Obsolete
Number of LABs/CLBs	19811
Number of Logic Elements/Cells	420000
Total RAM Bits	23625728
Number of I/O	544
Number of Gates	-
Voltage - Supply	1.07V ~ 1.13V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1152-BBGA, FCBGA Exposed Pad
Supplier Device Package	1152-FBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5agxfb5h6f35c6n

Symbol	Description	Condition	Minimum(7)	Typical	Maximum(7)	Unit
$V_{CC\_AUX\_SHARED}$	HPS auxiliary power supply	—	2.375	2.5	2.625	V

Related Information

Recommended Operating Conditions on page 1-4
Provides the steady-state voltage values for the FPGA portion of the device.

DC Characteristics

Supply Current and Power Consumption

Altera offers two ways to estimate power for your design—the Excel-based Early Power Estimator (EPE) and the Quartus® Prime PowerPlay Power Analyzer feature.

Use the Excel-based EPE before you start your design to estimate the supply current for your design. The EPE provides a magnitude estimate of the device power because these currents vary greatly with the resources you use.

The Quartus Prime PowerPlay Power Analyzer provides better quality estimates based on the specifics of the design after you complete place-and-route. The PowerPlay Power Analyzer can apply a combination of user-entered, simulation-derived, and estimated signal activities that, when combined with detailed circuit models, yields very accurate power estimates.

Related Information

- PowerPlay Early Power Estimator User Guide
  Provides more information about power estimation tools.
- PowerPlay Power Analysis chapter, Quartus Prime Handbook
  Provides more information about power estimation tools.

(7) The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

- Transceiver Specifications for Arria V GT and ST Devices on page 1-29
  Provides the specifications for transmitter, receiver, and reference clock I/O pin.

Switching Characteristics

This section provides performance characteristics of Arria V core and periphery blocks.

Transceiver Performance Specifications

Transceiver Specifications for Arria V GX and SX Devices

Table 1-20: Reference Clock Specifications for Arria V GX and SX Devices

Symbol/Description	Condition	Transceiver Speed Grade 4			Transceiver Speed Grade 6			Unit
		Min	Typ	Max	Min	Typ	Max	
Supported I/O standards	1.2 V PCML, 1.4 V PCML,1.5 V PCML, 2.5 V PCML, Differential LVPECL[23], HCSL, and LVDS							
Input frequency from REFCLK input pins	—	27	—	710	27	—	710	MHz
Rise time	Measure at ±60 mV of differential signal[24]	—	—	400	—	—	400	ps
Fall time	Measure at ±60 mV of differential signal[24]	—	—	400	—	—	400	ps
Duty cycle	—	45	—	55	45	—	55	%
Peak-to-peak differential input voltage	—	200	—	300[25]/ 2000	200	—	300[25]/ 2000	mV

(23) Differential LVPECL signal levels must comply to the minimum and maximum peak-to-peak differential input voltage specified in this table.
(24) REFCLK performance requires to meet transmitter REFCLK phase noise specification.
(25) The maximum peak-to peak differential input voltage of 300 mV is allowed for DC coupled link.

Symbol/Description	Condition	Transceiver Speed Grade 4			Transceiver Speed Grade 6			Unit
		Min	Typ	Max	Min	Typ	Max	
Minimum differential eye opening at the receiver serial input pins[30]	—	100	—	—	100	—	—	mV
V_{ICM} (AC coupled)	—	—	0.7/0.75/ 0.8[31]	—	—	0.7/0.75/ 0.8 [31]	—	mV
V_{ICM} (DC coupled)	≤ 3.2Gbps[32]	670	700	730	670	700	730	mV
Differential on-chip termination resistors	85-Ω setting	—	85	—	—	85	—	Ω
	100-Ω setting	—	100	—	—	100	—	Ω
	120-Ω setting	—	120	—	—	120	—	Ω
	150-Ω setting	—	150	—	—	150	—	Ω
t_{LTR}[33]	—	—	—	10	—	—	10	µs
t_{LTD}[34]	—	4	—	—	4	—	—	µs
t_{LTD_manual}[35]	—	4	—	—	4	—	—	µs
$t_{LTR\_LTD\_manual}$[36]	—	15	—	—	15	—	—	µs
Programmable ppm detector[37]	—	±62.5, 100, 125, 200, 250, 300, 500, and 1000						ppm

(30) The differential eye opening specification at the receiver input pins assumes that you have disabled the **Receiver Equalization** feature. If you enable the **Receiver Equalization** feature, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.

(31) The AC coupled V_{ICM} = 700 mV for Arria V GX and SX in PCIe mode only. The AC coupled V_{ICM} = 750 mV for Arria V GT and ST in PCIe mode only.

(32) For standard protocol compliance, use AC coupling.

(33) t_{LTR} is the time required for the receive CDR to lock to the input reference clock frequency after coming out of reset.

(34) t_{LTD} is time required for the receiver CDR to start recovering valid data after the `rx_is_lockedtodata` signal goes high.

(35) t_{LTD_manual} is the time required for the receiver CDR to start recovering valid data after the `rx_is_lockedtodata` signal goes high when the CDR is functioning in the manual mode.

(36) $t_{LTR\_LTD\_manual}$ is the time the receiver CDR must be kept in lock to reference (LTR) mode after the `rx_is_lockedtoref` signal goes high when the CDR is functioning in the manual mode.

DSP Block Performance Specifications

Table 1-37: DSP Block Performance Specifications for Arria V Devices

Mode		Performance			Unit
		–I3, –C4	–I5, –C5	–C6	
Modes using One DSP Block	Independent 9 × 9 multiplication	370	310	220	MHz
	Independent 18 × 19 multiplication	370	310	220	MHz
	Independent 18 × 25 multiplication	370	310	220	MHz
	Independent 20 × 24 multiplication	370	310	220	MHz
	Independent 27 × 27 multiplication	310	250	200	MHz
	Two 18 × 19 multiplier adder mode	370	310	220	MHz
	18 × 18 multiplier added summed with 36-bit input	370	310	220	MHz
Modes using Two DSP Blocks	Complex 18 × 19 multiplication	370	310	220	MHz

Memory Block Performance Specifications

To achieve the maximum memory block performance, use a memory block clock that comes through global clock routing from an on-chip PLL and set to 50% output duty cycle. Use the Quartus Prime software to report timing for the memory block clocking schemes.

When you use the error detection cyclical redundancy check (CRC) feature, there is no degradation in f_{MAX}.

Symbol		Condition	–I3, –C4			–I5, –C5			–C6			Unit
			Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
	TCCS	True Differential I/O Standards	—	—	150	—	—	150	—	—	150	ps
		Emulated Differential I/O Standards	—	—	300	—	—	300	—	—	300	ps
Receiver	True Differential I/O Standards - $f_{HSDRDPA}$ (data rate)	SERDES factor J =3 to 10[76]	150	—	1250	150	—	1250	150	—	1050	Mbps
		SERDES factor J ≥ 8 with DPA[76][78]	150	—	1600	150	—	1500	150	—	1250	Mbps
	f_{HSDR} (data rate)	SERDES factor J = 3 to 10	[77]	—	[83]	[77]	—	[83]	[77]	—	[83]	Mbps
		SERDES factor J = 1 to 2, uses DDR registers	[77]	—	[79]	[77]	—	[79]	[77]	—	[79]	Mbps
DPA Mode	DPA run length	—	—	—	10000	—	—	10000	—	—	10000	UI
Soft-CDR Mode	Soft-CDR ppm tolerance	—	—	—	300	—	—	300	—	—	300	±ppm
Non-DPA Mode	Sampling Window	—	—	—	300	—	—	300	—	—	300	ps

(83) You can estimate the achievable maximum data rate for non-DPA mode by performing link timing closure analysis. You must consider the board skew margin, transmitter delay margin, and receiver sampling margin to determine the maximum data rate supported.

After the Boot ROM code exits and control is passed to the preloader, software can adjust the value of `drvsel` and `smplsel` via the system manager. `drvsel` can be set from 1 to 7 and `smplsel` can be set from 0 to 7. While the preloader is executing, the values for `SDMMC_CLK` and `SDMMC_CLK_OUT` increase to a maximum of 200 MHz and 50 MHz respectively.

The SD/MMC interface calibration support will be available in a future release of the preloader through the SoC EDS software update.

Symbol	Description	Min	Max	Unit
T_{sdmmc_clk} (internal reference clock)	SDMMC_CLK clock period (Identification mode)	20	—	ns
	SDMMC_CLK clock period (Default speed mode)	5	—	ns
	SDMMC_CLK clock period (High speed mode)	5	—	ns
$T_{sdmmc\_clk\_out}$ (interface output clock)	SDMMC_CLK_OUT clock period (Identification mode)	2500	—	ns
	SDMMC_CLK_OUT clock period (Default speed mode)	40	—	ns
	SDMMC_CLK_OUT clock period (High speed mode)	20	—	ns
$T_{dutycycle}$	SDMMC_CLK_OUT duty cycle	45	55	%
T_d	SDMMC_CMD/SDMMC_D output delay	(T_{sdmmc_clk} × `drvsel`)/2 – 1.23 [87]	(T_{sdmmc_clk} × `drvsel`)/2 + 1.69 [87]	ns
T_{su}	Input setup time	1.05 – (T_{sdmmc_clk} × `smplsel`)/2 [88]	—	ns
T_h	Input hold time	(T_{sdmmc_clk} × `smplsel`)/2 [88]	—	ns

(87) `drvsel` is the drive clock phase shift select value.
(88) `smplsel` is the sample clock phase shift select value.

Table 1-57: RGMII RX Timing Requirements for Arria V Devices

Symbol	Description	Min	Typ	Unit
T_{clk} (1000Base-T)	RX_CLK clock period	—	8	ns
T_{clk} (100Base-T)	RX_CLK clock period	—	40	ns
T_{clk} (10Base-T)	RX_CLK clock period	—	400	ns
T_{su}	RX_D/RX_CTL setup time	1	—	ns
T_h	RX_D/RX_CTL hold time	1	—	ns

Figure 1-14: RGMII RX Timing Diagram

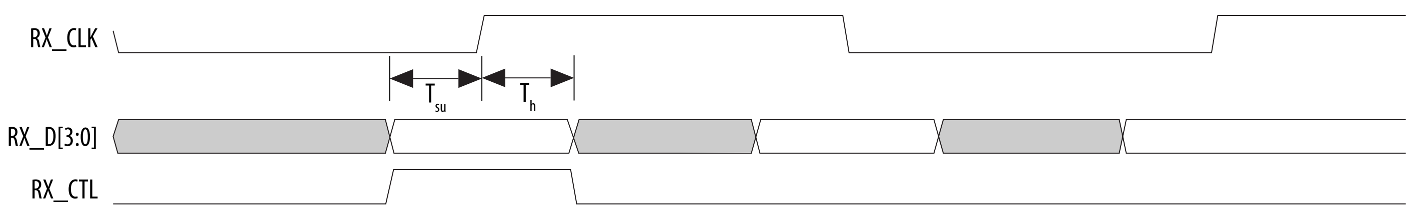
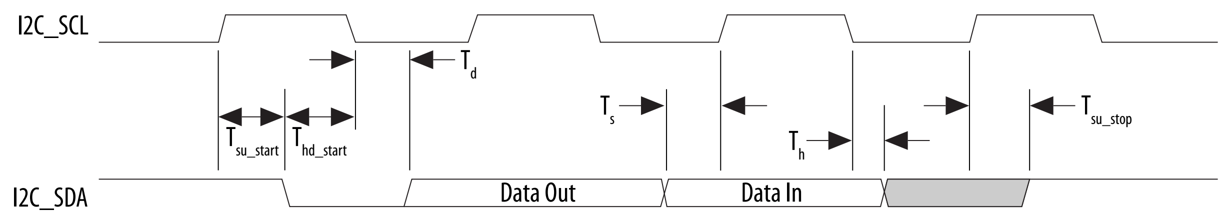


Table 1-58: Management Data Input/Output (MDIO) Timing Requirements for Arria V Devices

Symbol	Description	Min	Typ	Max	Unit
T_{clk}	MDC clock period	—	400	—	ns
T_d	MDC to MDIO output data delay	10	—	20	ns
T_s	Setup time for MDIO data	10	—	—	ns
T_h	Hold time for MDIO data	0	—	—	ns

Figure 1-16: I²C Timing Diagram



NAND Timing Characteristics

Table 1-60: NAND ONFI 1.0 Timing Requirements for Arria V Devices

The NAND controller supports Open NAND FLASH Interface (ONFI) 1.0 Mode 5 timing as well as legacy NAND devices. This table lists the requirements for ONFI 1.0 mode 5 timing. The HPS NAND controller can meet this timing by programming the `C4` output of the main HPS PLL and timing registers provided in the NAND controller.

Symbol	Description	Min	Max	Unit
T_{wp}(89)	Write enable pulse width	10	—	ns
T_{wh}(89)	Write enable hold time	7	—	ns
T_{rp}(89)	Read enable pulse width	10	—	ns
T_{reh}(89)	Read enable hold time	7	—	ns
T_{clesu}(89)	Command latch enable to write enable setup time	10	—	ns
T_{cleh}(89)	Command latch enable to write enable hold time	5	—	ns
T_{cesu}(89)	Chip enable to write enable setup time	15	—	ns
T_{ceh}(89)	Chip enable to write enable hold time	5	—	ns
T_{alesu}(89)	Address latch enable to write enable setup time	10	—	ns
T_{aleh}(89)	Address latch enable to write enable hold time	5	—	ns
T_{dsu}(89)	Data to write enable setup time	10	—	ns

(89) Timing of the NAND interface is controlled through the NAND configuration registers.

Symbol	Parameter	Minimum	Maximum	Unit
t_{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	—	—
t_{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t_{CD2CU} + (T_{init} × CLKUSR period)	—	—
T_{init}	Number of clock cycles required for device initialization	8,576	—	Cycles

Related Information

FPP Configuration Timing

Provides the FPP configuration timing waveforms.

AS Configuration Timing

Table 1-68: AS Timing Parameters for AS ×1 and ×4 Configurations in Arria V Devices

The minimum and maximum numbers apply to both the internal oscillator and CLKUSR when either one is used as the clock source for device configuration.

The t_{CF2CD}, t_{CF2ST0}, t_{CFG}, t_{STATUS}, and t_{CF2ST1} timing parameters are identical to the timing parameters for passive serial (PS) mode listed in PS Timing Parameters for Arria V Devices table. You can obtain the t_{CF2ST1} value if you do not delay configuration by externally holding nSTATUS low.

Symbol	Parameter	Minimum	Maximum	Unit
t_{CO}	DCLK falling edge to the AS_DATA0/ASDO output	—	2	ns
t_{SU}	Data setup time before the falling edge on DCLK	1.5	—	ns
t_{DH}	Data hold time after the falling edge on DCLK	0	—	ns
t_{CD2UM}	CONF_DONE high to user mode	175	437	µs
t_{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	—	—
t_{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t_{CD2CU} + (T_{init} × CLKUSR period)	—	—
T_{init}	Number of clock cycles required for device initialization	8,576	—	Cycles

Related Information

- **PS Configuration Timing** on page 1-81
- **AS Configuration Timing**
  Provides the AS configuration timing waveform.

DCLK Frequency Specification in the AS Configuration Scheme

Table 1-69: DCLK Frequency Specification in the AS Configuration Scheme

This table lists the internal clock frequency specification for the AS configuration scheme. The DCLK frequency specification applies when you use the internal oscillator as the configuration clock source. The AS multi-device configuration scheme does not support DCLK frequency of 100 MHz.

Parameter	Minimum	Typical	Maximum	Unit
DCLK frequency in AS configuration scheme	5.3	7.9	12.5	MHz
	10.6	15.7	25.0	MHz
	21.3	31.4	50.0	MHz
	42.6	62.9	100.0	MHz

PS Configuration Timing

Table 1-70: PS Timing Parameters for Arria V Devices

Symbol	Parameter	Minimum	Maximum	Unit
t_{CF2CD}	nCONFIG low to CONF_DONE low	—	600	ns
t_{CF2ST0}	nCONFIG low to nSTATUS low	—	600	ns
t_{CFG}	nCONFIG low pulse width	2	—	µs
t_{STATUS}	nSTATUS low pulse width	268	1506[103]	µs
t_{CF2ST1}	nCONFIG high to nSTATUS high	—	1506[104]	µs

(103) You can obtain this value if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.
(104) You can obtain this value if you do not delay configuration by externally holding nSTATUS low.

Symbol	Parameter	Minimum	Maximum	Unit
t_{CF2CK} (105)	nCONFIG high to first rising edge on DCLK	1506	—	µs
t_{ST2CK} (105)	nSTATUS high to first rising edge of DCLK	2	—	µs
t_{DSU}	DATA[] setup time before rising edge on DCLK	5.5	—	ns
t_{DH}	DATA[] hold time after rising edge on DCLK	0	—	ns
t_{CH}	DCLK high time	$0.45 \times 1/f_{MAX}$	—	s
t_{CL}	DCLK low time	$0.45 \times 1/f_{MAX}$	—	s
t_{CLK}	DCLK period	$1/f_{MAX}$	—	s
f_{MAX}	DCLK frequency	—	125	MHz
t_{CD2UM}	CONF_DONE high to user mode(106)	175	437	µs
t_{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	—	—
t_{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t_{CD2CU} + (T_{init} × CLKUSR period)	—	—
T_{init}	Number of clock cycles required for device initialization	8,576	—	Cycles

Related Information

PS Configuration Timing

Provides the PS configuration timing waveform.

(105) If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.

(106) The minimum and maximum numbers apply only if you chose the internal oscillator as the clock source for initializing the device.

Transceiver Power Supply Requirements

Table 2-7: Transceiver Power Supply Voltage Requirements for Arria V GZ Devices

<table>
<tr><th>Conditions</th><th>VCCR_GXB and VCCT_GXB [122]</th><th>VCCA_GXB</th><th>VCCH_GXB</th><th>Unit</th></tr>
<tr><td>If BOTH of the following conditions are true:
• Data rate > 10.3 Gbps.
• DFE is used.</td><td>1.05</td><td rowspan="2">3.0</td><td rowspan="3">1.5</td><td rowspan="3">V</td></tr>
<tr><td>If ANY of the following conditions are true [123] :
• ATX PLL is used.
• Data rate > 6.5Gbps.
• DFE (data rate ≤ 10.3 Gbps), AEQ, or EyeQ feature is used.</td><td>1.0</td></tr>
<tr><td>If ALL of the following conditions are true:
• ATX PLL is not used.
• Data rate ≤ 6.5Gbps.
• DFE, AEQ, and EyeQ are not used.</td><td>0.85</td><td>2.5</td></tr>
</table>

DC Characteristics

Supply Current

Standby current is the current drawn from the respective power rails used for power budgeting.

Use the Excel-based Early Power Estimator (EPE) to get supply current estimates for your design because these currents vary greatly with the resources you use.

(122) If the VCCR_GXB and VCCT_GXB supplies are set to 1.0 V or 1.05 V, they cannot be shared with the VCC core supply. If the VCCR_GXB and VCCT_GXB are set to 0.85 V, they can be shared with the VCC core supply.

(123) Choose this power supply voltage requirement option if you plan to upgrade your design later with any of the listed conditions.

Symbol	Description	Conditions	Resistance Tolerance		Unit
			C3, I3L	C4, I4	
25-Ω R_S	Internal series termination without calibration (25-Ω setting)	V_{CCIO} = 1.8 and 1.5 V	±40	±40	%
25-Ω R_S	Internal series termination without calibration (25-Ω setting)	V_{CCIO} = 1.2 V	±50	±50	%
50-Ω R_S	Internal series termination without calibration (50-Ω setting)	V_{CCIO} = 1.8 and 1.5 V	±40	±40	%
50-Ω R_S	Internal series termination without calibration (50-Ω setting)	V_{CCIO} = 1.2 V	±50	±50	%
100-Ω R_D	Internal differential termination (100-Ω setting)	V_{CCIO} = 2.5 V	±25	±25	%

Figure 2-1: OCT Variation Without Re-Calibration for Arria V GZ Devices

$$R_{OCT} = R_{SCAL} \left(1 + \left(\frac{dR}{dT} \times \triangle T\right) \pm \left(\frac{dR}{dV} \times \triangle V\right)\right)$$

Notes:
1. The R_{OCT} value shows the range of OCT resistance with the variation of temperature and V_{CCIO}.
2. R_{SCAL} is the OCT resistance value at power-up.
3. ΔT is the variation of temperature with respect to the temperature at power-up.
4. ΔV is the variation of voltage with respect to the V_{CCIO} at power-up.
5. dR/dT is the percentage change of R_{SCAL} with temperature.
6. dR/dV is the percentage change of R_{SCAL} with voltage.

Table 2-12: OCT Variation after Power-Up Calibration for Arria V GZ Devices

Valid for a V_{CCIO} range of ±5% and a temperature range of 0° to 85°C.

Symbol/Description	Conditions	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	
V_{ICM} (AC and DC coupled)	V_{CCR_GXB} = 0.85 V full bandwidth	—	600	—	—	600	—	mV
	V_{CCR_GXB} = 0.85 V half bandwidth	—	600	—	—	600	—	mV
	V_{CCR_GXB} = 1.0 V full bandwidth	—	700	—	—	700	—	mV
	V_{CCR_GXB} = 1.0 V half bandwidth	—	700	—	—	700	—	mV
t_{LTR} (149)	—	—	—	10	—	—	10	µs
t_{LTD} (150)	—	4	—	—	4	—	—	µs
t_{LTD_manual} (151)	—	4	—	—	4	—	—	µs
$t_{LTR\_LTD\_manual}$ (152)	—	15	—	—	15	—	—	µs
Programmable equalization (AC Gain)	Full bandwidth (6.25 GHz) Half bandwidth (3.125 GHz)	—	—	16	—	—	16	dB

(149) t_{LTR} is the time required for the receive CDR to lock to the input reference clock frequency after coming out of reset.

(150) t_{LTD} is time required for the receiver CDR to start recovering valid data after the `rx_is_lockedtodata` signal goes high.

(151) t_{LTD_manual} is the time required for the receiver CDR to start recovering valid data after the `rx_is_lockedtodata` signal goes high when the CDR is functioning in the manual mode.

(152) $t_{LTR\_LTD\_manual}$ is the time the receiver CDR must be kept in lock to reference (LTR) mode after the `rx_is_lockedtoref` signal goes high when the CDR is functioning in the manual mode.

Symbol/Description	Conditions	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	
Programmable DC gain	DC gain setting = 0	—	0	—	—	0	—	dB
	DC gain setting = 1	—	2	—	—	2	—	dB
	DC gain setting = 2	—	4	—	—	4	—	dB
	DC gain setting = 3	—	6	—	—	6	—	dB
	DC gain setting = 4	—	8	—	—	8	—	dB

Related Information

Arria V Device Overview

For more information about device ordering codes.

Transmitter

Table 2-25: Transmitter Specifications for Arria V GZ Devices

Speed grades shown refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the *Arria V Device Overview*.

Symbol/Description	Conditions	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	
Supported I/O Standards	1.4-V and 1.5-V PCML							
Data rate (Standard PCS)	—	600	—	9900	600	—	8800	Mbps
Data rate (10G PCS)	—	600	—	12500	600	—	10312.5	Mbps

Symbol/Description	Conditions	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	
Supported data range	—	600	—	3250/ 3125[158]	600	—	3250/ 3125 [158]	Mbps
$t_{pll\_powerdown}$[159]	—	1	—	—	1	—	—	µs
t_{pll_lock} [160]	—	—	—	10		—	10	µs

Related Information

Arria V Device Overview

For more information about device ordering codes.

Clock Network Data Rate

Table 2-29: Clock Network Maximum Data Rate Transmitter Specifications

Valid data rates below the maximum specified in this table depend on the reference clock frequency and the PLL counter settings. Check the MegaWizard message during the PHY IP instantiation.

Clock Network	ATX PLL			CMU PLL [161]			fPLL		
	Non-bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span	Non-bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span	Non-bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span
x1 [162]	12.5	—	6	12.5	—	6	3.125	—	3
x6 [162]	—	12.5	6	—	12.5	6	—	3.125	6
x6 PLL Feedback [163]	—	12.5	Side-wide	—	12.5	Side-wide	—	—	—

(158) When you use fPLL as a TXPLL of the transceiver.
(159) $t_{pll\_powerdown}$ is the PLL powerdown minimum pulse width.
(160) t_{pll_lock} is the time required for the transmitter CMU/ATX PLL to lock to the input reference clock frequency after coming out of reset.
(161) ATX PLL is recommended at 8 Gbps and above data rates for improved jitter performance.
(162) Channel span is within a transceiver bank.
(163) Side-wide channel bonding is allowed up to the maximum supported by the PHY IP.

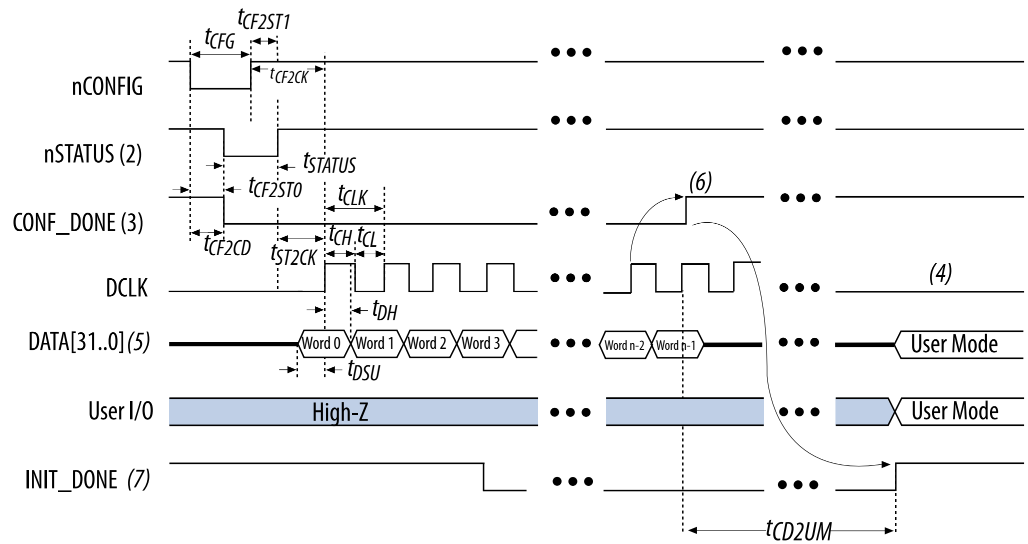
Symbol	Conditions	C3, I3L			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	
True Differential I/O Standards - $f_{HSDRDPA}$ (data rate)	SERDES factor J = 3 to 10 (192), (193), (194), (195), (196), (197)	150	—	1250	150	—	1050	Mbps
	SERDES factor J ≥ 4 LVDS RX with DPA (193), (195), (196), (197)	150	—	1600	150	—	1250	Mbps
	SERDES factor J = 2, uses DDR Registers	(198)	—	(199)	(198)	—	(199)	Mbps
	SERDES factor J = 1, uses SDR Register	(198)	—	(199)	(198)	—	(199)	Mbps
f_{HSDR} (data rate)	SERDES factor J = 3 to 10	(198)	—	(200)	(198)	—	(200)	Mbps
	SERDES factor J = 2, uses DDR Registers	(198)	—	(199)	(198)	—	(199)	Mbps
	SERDES factor J = 1, uses SDR Register	(198)	—	(199)	(198)	—	(199)	Mbps

(192) The F_{MAX} specification is based on the fast clock used for serial data. The interface F_{MAX} is also dependent on the parallel clock domain which is design dependent and requires timing analysis.
(193) Arria V GZ RX LVDS will need DPA. For Arria V GZ TX LVDS, the receiver side component must have DPA.
(194) Arria V GZ LVDS serialization and de-serialization factor needs to be x4 and above.
(195) Requires package skew compensation with PCB trace length.
(196) Do not mix single-ended I/O buffer within LVDS I/O bank.
(197) Chip-to-chip communication only with a maximum load of 5 pF.
(198) The minimum specification depends on the clock source (for example, the PLL and clock pin) and the clock routing resource (global, regional, or local) that you use. The I/O differential buffer and input register do not have a minimum toggle rate.
(199) The maximum ideal data rate is the SERDES factor (J) x the PLL maximum output frequency (fOUT) provided you can close the design timing and the signal integrity simulation is clean.
(200) You can estimate the achievable maximum data rate for non-DPA mode by performing link timing closure analysis. You must consider the board skew margin, transmitter delay margin, and receiver sampling margin to determine the maximum data rate supported.

FPP Configuration Timing when DCLK to DATA[] = 1

Figure 2-7: FPP Configuration Timing Waveform When the DCLK-to-DATA[] Ratio is 1

Timing waveform for FPP configuration when using a MAX® II or MAX V device as an external host.



Notes:

1. The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF_DONE are at logic-high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
2. After power-up, the Arria V GZ device holds nSTATUS low for the time of the POR delay.
3. After power-up, before and during configuration, CONF_DONE is low.
4. Do not leave DCLK floating after configuration. DCLK is ignored after configuration is complete. It can toggle high or low if required.
5. For FPP ×16, use DATA[15..0]. For FPP ×8, use DATA[7..0]. DATA[31..0] are available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings.
6. To ensure a successful configuration, send the entire configuration data to the Arria V GZ device. CONF_DONE is released high when the Arria V GZ device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
7. After the option bit to enable the INIT_DONE pin is configured into the device, the INIT_DONE goes low.

Table 2-60: PS Timing Parameters for Arria V GZ Devices

Symbol	Parameter	Minimum	Maximum	Unit
t_{CF2CD}	nCONFIG low to CONF_DONE low	—	600	ns
t_{CF2ST0}	nCONFIG low to nSTATUS low	—	600	ns
t_{CFG}	nCONFIG low pulse width	2	—	µs
t_{STATUS}	nSTATUS low pulse width	268	1,506 [217]	µs
t_{CF2ST1}	nCONFIG high to nSTATUS high	—	1,506 [218]	µs
t_{CF2CK} [219]	nCONFIG high to first rising edge on DCLK	1,506	—	µs
t_{ST2CK} [219]	nSTATUS high to first rising edge of DCLK	2	—	µs
t_{DSU}	DATA[] setup time before rising edge on DCLK	5.5	—	ns
t_{DH}	DATA[] hold time after rising edge on DCLK	0	—	ns
t_{CH}	DCLK high time	$0.45 \times 1/f_{MAX}$	—	s
t_{CL}	DCLK low time	$0.45 \times 1/f_{MAX}$	—	s
t_{CLK}	DCLK period	$1/f_{MAX}$	—	s
f_{MAX}	DCLK frequency	—	125	MHz
t_{CD2UM}	CONF_DONE high to user mode [220]	175	437	µs
t_{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	—	—
t_{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t_{CD2CU} + (8576 × CLKUSR period) [221]	—	—

(217) This value is applicable if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.
(218) This value is applicable if you do not delay configuration by externally holding the nSTATUS low.
(219) If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.
(220) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.

Term	Definition
t_C	High-speed receiver and transmitter input and output clock period.
TCCS (channel-to-channel-skew)	The timing difference between the fastest and slowest output edges, including t_{CO} variation and clock skew, across channels driven by the same PLL. The clock is included in the TCCS measurement (refer to the Timing Diagram figure under SW in this table).
t_{DUTY}	High-speed I/O block—Duty cycle on the high-speed transmitter output clock.
t_{FALL}	Signal high-to-low transition time (80-20%)
t_{INCCJ}	Cycle-to-cycle jitter tolerance on the PLL clock input.
t_{OUTPJ_IO}	Period jitter on the general purpose I/O driven by a PLL.
t_{OUTPJ_DC}	Period jitter on the dedicated clock output driven by a PLL.
t_{RISE}	Signal low-to-high transition time (20-80%)
Timing Unit Interval (TUI)	The timing budget allowed for skew, propagation delays, and the data sampling window. (TUI = 1/(receiver input clock frequency multiplication factor) = t_C/w)
$V_{CM(DC)}$	DC common mode input voltage.
V_{ICM}	Input common mode voltage—The common mode of the differential signal at the receiver.
V_{ID}	Input differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the receiver.
$V_{DIF(AC)}$	AC differential input voltage—Minimum AC input differential voltage required for switching.
$V_{DIF(DC)}$	DC differential input voltage— Minimum DC input differential voltage required for switching.
V_{IH}	Voltage input high—The minimum positive voltage applied to the input which is accepted by the device as a logic high.
$V_{IH(AC)}$	High-level AC input voltage
$V_{IH(DC)}$	High-level DC input voltage
V_{IL}	Voltage input low—The maximum positive voltage applied to the input which is accepted by the device as a logic low.
$V_{IL(AC)}$	Low-level AC input voltage
$V_{IL(DC)}$	Low-level DC input voltage